Chip Monolithic Ceramic Capacitors



Medium-voltage High-Capacitance for General-Use

■ Features

- A new monolithic structure for small, high capacitance capable of operating at high voltage levels
- 2. Sn-plated external electrodes realized good solderability.
- 3. Use the GRM18/21/31 types with flow or reflow soldering, and other types with reflow soldering only.

■ Applications

- Ideal for use as a hot-cold coupling for DC/DC converter.
- 2. Ideal for use on line filters and ringer detectors for telephones, facsimiles and modems.
- 3. Ideal for use on diode-snubber circuits for switching power supplies.

22	•							
Part Number		Dimensions (mm)						
T dit Hairibei	L	W	T	е	g min.			
GRM188	1.6 ±0.1	0.8 ±0.1	0.8 ±0.1	0.2 to 0.5	0.4			
GRM21A	2.0 ±0.2	1.25 ±0.2	1.0 +0,-0.3		0.7			
GRM21B			1.25 ±0.2					
GRM31B	3.2 ±0.2	1.6 ±0.2	1.25 +0,-0.3	1				
GRM31C			1.6 ±0.2		1.2			
GRM32Q	3.2 ±0.3	2.5 ±0.2	1.5 +0,-0.3	0.3 min.	1.2			
GRM32D	3.∠ ±0.3	2.5 IU.2	2.0 +0,-0.3					
GRM43Q	4.5.10.4	22102	1.5 +0,-0.3]	2.2			
GRM43D	4.5 ±0.4	3.2 ±0.3	2.0 +0,-0.3		2.2			
GRM55D	5.7 ±0.4	5.0 ±0.4	2.0 +0,-0.3		3.2*			

* GRM55DR73A	:	2.5mm	min.
--------------	---	-------	------

Part Number	Rated Voltage (V)	TC Code (Standard)	Capacitance	Length L (mm)	Width W (mm)	Thickness T (mm)	Electrode g min. (mm)	Electrode e (mm)
GRM188R72E221KW07D	DC250	X7R (EIA)	220pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM188R72E331KW07D	DC250	X7R (EIA)	330pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM188R72E471KW07D	DC250	X7R (EIA)	470pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM188R72E681KW07D	DC250	X7R (EIA)	680pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM188R72E102KW07D	DC250	X7R (EIA)	1000pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM21AR72E102KW01D	DC250	X7R (EIA)	1000pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM188R72E152KW07D	DC250	X7R (EIA)	1500pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM21AR72E152KW01D	DC250	X7R (EIA)	1500pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM188R72E222KW07D	DC250	X7R (EIA)	2200pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM21AR72E222KW01D	DC250	X7R (EIA)	2200pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM21AR72E332KW01D	DC250	X7R (EIA)	3300pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM21AR72E472KW01D	DC250	X7R (EIA)	4700pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM21AR72E682KW01D	DC250	X7R (EIA)	6800pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM21BR72E103KW03L	DC250	X7R (EIA)	10000pF ±10%	2.0	1.25	1.25	0.7	0.3 min.
GRM31BR72E153KW01L	DC250	X7R (EIA)	15000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72E223KW01L	DC250	X7R (EIA)	22000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31CR72E333KW03L	DC250	X7R (EIA)	33000pF ±10%	3.2	1.6	1.6	1.2	0.3 min.
GRM31CR72E473KW03L	DC250	X7R (EIA)	47000pF ±10%	3.2	1.6	1.6	1.2	0.3 min.
GRM32QR72E683KW01L	DC250	X7R (EIA)	68000pF ±10%	3.2	2.5	1.5	1.2	0.3 min.
GRM31CR72E104KW03L	DC250	X7R (EIA)	0.10μF ±10%	3.2	1.6	1.6	1.2	0.3 min.
GRM32DR72E104KW01L	DC250	X7R (EIA)	0.10μF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM43QR72E154KW01L	DC250	X7R (EIA)	0.15μF ±10%	4.5	3.2	1.5	2.2	0.3 min.
GRM32DR72E224KW01L	DC250	X7R (EIA)	0.22μF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM43DR72E224KW01L	DC250	X7R (EIA)	0.22μF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM43DR72E334KW01L	DC250	X7R (EIA)	0.33μF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM55DR72E334KW01L	DC250	X7R (EIA)	0.33μF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM43DR72E474KW01L	DC250	X7R (EIA)	0.47μF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM55DR72E474KW01L	DC250	X7R (EIA)	0.47μF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM55DR72E105KW01L	DC250	X7R (EIA)	1.0μF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM31BR72J102KW01L	DC630	X7R (EIA)	1000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J152KW01L	DC630	X7R (EIA)	1500pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J222KW01L	DC630	X7R (EIA)	2200pF ±10%	3.2	1.6	1.25	1.2	0.3 min.

Continued from the preceding page.

Part Number	Rated Voltage (V)	TC Code (Standard)	Capacitance	Length L (mm)	Width W (mm)	Thickness T (mm)	Electrode g min. (mm)	Electrode e (mm)
GRM31BR72J332KW01L	DC630	X7R (EIA)	3300pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J472KW01L	DC630	X7R (EIA)	4700pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J682KW01L	DC630	X7R (EIA)	6800pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J103KW01L	DC630	X7R (EIA)	10000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31CR72J153KW03L	DC630	X7R (EIA)	15000pF ±10%	3.2	1.6	1.6	1.2	0.3 min.
GRM32QR72J223KW01L	DC630	X7R (EIA)	22000pF ±10%	3.2	2.5	1.5	1.2	0.3 min.
GRM32DR72J333KW01L	DC630	X7R (EIA)	33000pF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM32DR72J473KW01L	DC630	X7R (EIA)	47000pF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM43QR72J683KW01L	DC630	X7R (EIA)	68000pF ±10%	4.5	3.2	1.5	2.2	0.3 min.
GRM43DR72J104KW01L	DC630	X7R (EIA)	0.10μF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM55DR72J154KW01L	DC630	X7R (EIA)	0.15μF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM55DR72J224KW01L	DC630	X7R (EIA)	0.22μF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM31BR73A102KW01L	DC1000	X7R (EIA)	1000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR73A152KW01L	DC1000	X7R (EIA)	1500pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR73A222KW01L	DC1000	X7R (EIA)	2200pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR73A332KW01L	DC1000	X7R (EIA)	3300pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR73A472KW01L	DC1000	X7R (EIA)	4700pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM32QR73A682KW01L	DC1000	X7R (EIA)	6800pF ±10%	3.2	2.5	1.5	1.2	0.3 min.
GRM32QR73A103KW01L	DC1000	X7R (EIA)	10000pF ±10%	3.2	2.5	1.5	1.2	0.3 min.
GRM32DR73A153KW01L	DC1000	X7R (EIA)	15000pF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM32DR73A223KW01L	DC1000	X7R (EIA)	22000pF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM43DR73A333KW01L	DC1000	X7R (EIA)	33000pF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM43DR73A473KW01L	DC1000	X7R (EIA)	47000pF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM55DR73A104KW01L	DC1000	X7R (EIA)	0.10μF ±10%	5.7	5.0	2.0	2.5	0.3 min.

Specifications and Test Methods

No.	Item Specifications	Test Method		
1	Operating Temperature Range -55 to +125℃	-		
2	Appearance No defects or abnormalities	Visual inspection		
3	Dimensions Within the specified dimensions	Using calipers		
4	Dielectric Strength No defects or abnormalities	No failure should be observed when 150% of the rated voltage (200% of the rated voltage in case of rated voltage: DC250V, 120% of the rated voltage in case of rated voltage: DC1kV) is applied between the terminations for 1 to 5 sec., provided the charge/discharge current is less than 50mA.		
5	Insulation Resistance (I.R.) $C \ge 0.01 \mu F$: More than $100 M \Omega \cdot \mu F$ $C < 0.01 \mu F$: More than $10,000 M \Omega$	The insulation resistance should be measured with DC500±50V (DC250±50V in case of rated voltage : DC250V) and within 60±5 sec. of charging.		
6	Capacitance Within the specified tolerance	The capacitance/D.F. should be measured at 25°C at a frequency of 1±0.2kHz and a voltage of AC1±0.2V (r.m.s.) •Pretreatment		
7	Dissipation Factor (D.F.) 0.025 max.	Perform a heat treatment at 150^{+0}_{-10} °C for 60 ± 5 min. and then let sit for 24 ± 2 hrs. at *room condition.		
8	Capacitance Temperature Characteristics Cap. Change Within ±15% (Temp. Range : −55 to +125°C)	The range of capacitance change compared with the 25°C value within -55 to +125°C should be within the specified range. • Pretreatment Perform a heat treatment at 150 +0 °C for 60±5 min. and then let sit for 24±2 hrs. at *room condition.		
9	Adhesive Strength of Termination No removal of the terminations or other defect should occur.	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 1 using a eutectic solder. Then apply 10N force in the direction of the arrow. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. 10N (5N: Size 1.6×0.8mm only), 10±1s Speed: 1.0mm/s Glass Epoxy Board		
		Fig. 1		
10	Appearance No defects or abnormalities Capacitance Within the specified tolerance Vibration Resistance	Solder the capacitor to the test jig (glass epoxy board). The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 min. This motion should be applied for a period of 2 hrs. in each 3 mutually perpendicular directions (total of 6 hrs.).		
	D.F. 0.025 max.	Solder resist Glass Epoxy Board		
	No cracking or marking defects should occur.	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 2 using a sutectic solder		
11	Deflection LXW Dimension (mm)	in Fig. 2 using a eutectic solder. Then apply a force in the direction shown in Fig. 3. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. 20 50 Pressurizing speed: 1.0mm/s Pressurize Pressurize Pressurize (in mm) Fig. 3		
	1.6×0.8 1.0 3.0 2.0×1.25 1.2 4.0 3.2×1.6 2.2 5.0 3.2×2.5 2.2 5.0 4.5×3.2 3.5 7.0	1.2 1.65 2.0		

^{* &}quot;Room condition" Temperature : 15 to 35°C, Relative humidity : 45 to 75%, Atmospheric pressure : 86 to 106kPa





Specifications and Test Methods

No.	lo. Item		Specifications	Test Method					
12	Solderability of Termination		75% of the terminations are to be soldered evenly and continuously.	rosin (JIS-K-5 Immerse in eu	nmerse the capacitor in a solution of ethanol (JIS-K-8101) and usin (JIS-K-5902) (25% rosin in weight proportion). nmerse in eutectic solder solution for 2±0.5 sec. at 235±5°C. nmersing speed: 25±2.5mm/s				
		Appearance	No marking defects		apacitor at 120 to 150℃* for 1 r				
		Capacitance Change	Within ±10%	10±1 sec. Let	Immerse the capacitor in eutectic solder solution at 260±5°C for 10±1 sec. Let sit at *room condition for 24±2 hrs., then measure. •Immersing speed : 25±2.5mm/s				
	Desistance	D.F.	0.025 max.	Pretreatment					
13	Resistance to Soldering Heat	I.R.	C≥0.01μF : More than 100MΩ • μF C<0.01μF : More than 10,000MΩ		Perform a heat treatment at 150±1% for 60±5 n let sit for 24±2 hrs. at *room condition.				
				*Preheating f	or more than 3.2×2.5mm				
		Dielectric	In accordance with item No.4	Step	Temperature	Time			
		Strength			100℃ to 120℃ 170℃ to 200℃	1 min. 1 min.			
		Appearance	No marking defects		tor to the supporting jig (glass of a eutectic solder.	epoxy board) shown			
		Capacitance Change	Within ±7.5%		cycles according to the 4 heat	treatments listed in			
		D.F.	0.025 max.	Let sit for 24±2 hrs. at *room condition, then measure.					
		I.R.	C≥0.01μF : More than 100MΩ • μF	Step	Temperature (°C)	Time (min.)			
			C<0.01μF : More than 10,000MΩ	1	Min. Operating Temp.±3 Room Temp.	30±3 2 to 3			
				3	Max. Operating Temp.±2	30±3			
				4	Room Temp.	2 to 3			
		Dielectric Strength	In accordance with item No.4	Perform a heat treatment at 150 ± 18° € for 60±5 min. and then let sit for 24±2 hrs. at *room condition. Solder resist Glass Epoxy Board					
					Fig. 4				
		Appearance	No marking defects						
		Capacitance Change	Within ±15%	Let the capac	itor sit at 40±2℃ and relative h ·s.	umidity of 90 to 95%			
15	Humidity (Steady	D.F.	0.05 max.	Remove and measure.	let sit for 24±2 hrs. at *room co	ondition, then			
	State)	I.R.	$C \ge 0.01 \mu F$: More than $10 M \Omega \cdot \mu F$ C<0.01 μF : More than 1,000 μG	•Pretreatmen	t eat treatment at 150±₁%℃ for 6	60±5 min. and then			
		Dielectric Strength	In accordance with item No.4	let sit for 24±	-2 hrs. at *room condition.				
		Appearance	No marking defects	Apply 120% c	of the rated voltage (150% of th	e rated voltage in			
		Capacitance Change	Within ±15% (rated voltage : DC250V, DC630V) Within ±20% (rated voltage : DC1kV)	case of rated case of rated	voltage : DC250V, 110% of the voltage : DC1kV) for 1,000 \pm 45	rated voltage in hrs. at maximum			
,	Lifo	D.F.	0.05 max.		perature ±3°C. Remove and le	t sit for 24 ±2 hrs. a			
16	Life -	I.R.	C≧0.01μF : More than 10MΩ • μF C<0.01μF : More than 1,000MΩ		scharge current is less than 50	mA.			
		Dielectric Strength	In accordance with item No.4		Itage for 60±5 min. at test tem let sit for 24±2 hrs. at *room of	•			
L		Appearance	No marking defects						
	Humidity	Capacitance Change	Within ±15%	Apply the rate	d voltage at 40±2℃ and relativ ^{:2} 4 hrs.	e humidity of 90 to			
	Loading (Application :	D.F.	0.05 max.	Remove and	let sit for 24±2 hrs. at *room co	ondition, then			
17	DC250V,	D.1.	C≥0.01μF : More than 10MΩ • μF	measure.	+				
DC	DC630V item)	I.R.	C<0.01μF : More than 1,000MΩ C<0.01μF : More than 1,000MΩ		Itage for 60±5 min. at test tem	•			
		Dielectric Strength	In accordance with item No.4	Kernove and	let sit for 24±2 hrs. at *room of	ondition.			

^{* &}quot;Room condition" Temperature : 15 to 35°C, Relative humidity : 45 to 75%, Atmospheric pressure : 86 to 106kPa